TOPFLIGHT INNOVATIONS

Functional and Intelligent Designs

Topflight's years of experience in printing and converting have led to the design and manufacture of many unique, functional products. Capabilities include intricate die-cutting, printed conductives, multi-ply constructions, flag labels, specialty seals, and deadened or zone coated adhesives.

Product engineers will work with you to create the most effective and affordable product possible, ensuring that it's designed for manufacturability.

- ✓ Precision die-cutting, laminating, and slitting for delivery in rolls, cards, or individual components. Tolerances as tight as ±0.001″ when using flat bed dies.
- ✓ Prototypes or raw material samples from lab using laser, flying knife, bench top flatbed punch press, or laminator
- ✓ Professional design engineers with decades of experience
- ✓ Printing flexo, letterpress, rotary screen, roll-to-roll flatbed screen, combination letterpress/rotary screen or flexo/screen, hot stamping, digital. Up to 12 stations inline.
- ✓ Specialty inks radiopaque, conductive, chemically reactive, security, chromic (thermo, hydro, photo), iridescent. UV, solvent, water based systems available.
- ✓ Engineer-to-engineer design support
- ✓ CAD formats accepted Illustrator ai, Corel Draw, DWG AutoCAD or DXF file.
- ✓ RFID converting & testing
- ✓ Conductive inks PTF silver, carbon, and silver/silver chloride and Nano-particle graphene and silver
- ✓ Copper and aluminum etching
- ✓ Adhesives deadened, printed, adhesive free windows, inert, skin friendly
- ✓ Low outgassing, non-reactive materials
- ✓ Hydrophilic and hydrophobic adhesives & coatings
- ✓ Low fluorescing materials
- ✓ Light-blocking, moisture barrier foils



Topflight's prototype lab allows customers to test multiple design iterations before purchasing expensive tooling. Matching production equipment ensures full scalability to production quantities as required.



Complex multi-layer laminated parts can be produced on servo-driven equipment with precision tension control and reregistration of up to 8 layers of differential material.